KINGSTATE ELECTRONICS CORPORATION

10F, NO.69-11, SEC.2, CHUNG CHENG E.RD., TAMSHUI DIST, NEW TAIPEI CITY TAIWAN.

Dear Sir / Madam Date: 2022/09/30

PRODUCT CHANGE NOTICE:

We hereby announce that the part no.: **KTG0912CL** has been executed with a

change. The updated product will be: **KTG0912CL** VERSION: **TKS-5028-1.1**

Change	Before	After
外觀變更 Change of product appearance 正面: 新舊結構無差異 Front: no difference between old and new structures		
側面:舊結構油墨印字,新結 構鐳射印字,優點新結構镭射印 字更环保 Side: old structure ink printing, new structure laser printing, Advantages New structure Laser printing is more environmentally friendly	KTG0912CL 4221 ⊕	RECORD 201
背面:舊結構環氧表面有兩個電子料痕跡;新結構環氧表面有一個電子料痕跡 Back: There are two traces of electronic materials on the		

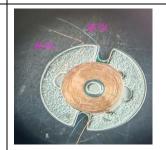
epoxy surface of the old structure; There is an electronic material mark on the epoxy surface of the new structure

内部结构:

舊結構雙根漆包線,四線頭,线 径为0.03mm,雙缺口支架;新 結構單根漆包線,雙線頭,线径 为0.035mm,單缺口支架,優點 線頭由雙線減少為單線,線徑加 大,從而有效降低斷線風險从, 提升產品品質穩定性



The old structure has two enamelled wires, four heads, wire diameter of 0.03mm, and double notch support; Single enamelled wire of new structure, double wire head, wire diameter 0.035mm, single notch support, Advantages The thread head is reduced from double line to single line, and the wire diameter is increased, thus effectively reducing the risk of wire breakage and improving the stability of product quality





内部结构:

舊結構用 504 粘 PCB;

新結構用 KE44 粘 PCB,優點 504 雙組分樹脂膠水,產品在進行高溫以後,樹脂會存在脆化,降低粘性強度.KE44 硅膠在耐高溫性方面除滿足迴流焊的高溫,同時在高溫以後不會失效,同樣保持粘性,提升產品品質





Internal structure:

The old structure uses 504 to stick PCB;

Paste PCB with KE44 for new structure, Advantages: 504 two-component resin glue. After the product is subjected to high temperature, the resin will be brittle, reducing the viscosity strength In terms of high temperature resistance, KE44 silica gel not only meets the high temperature of reflow welding, but also will not fail after high temperature. It also maintains viscosity and improves product quality

内部结构:

舊結構為三極管驅動方式;

新結構為芯片驅動方式 Internal structure:

The old structure was driven by triode;

The new structure is chip driven







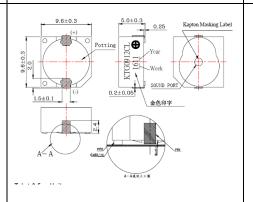


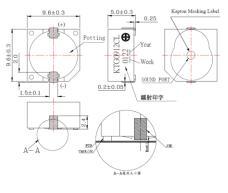
Change

外观尺寸说明:

变更前后尺寸无差异

About appearance and size: There is no difference in size before and after the change.





Change content

特性:

舊結構為三極管驱动方式,

频率实际值可控制在 2700±

300HZ 范围;新結構為芯片驱

动方式,频率实际值可控制在

2700±200HZ 范围, 優點新结构

采用IC驅動頻率可控制範圍更小,產品品質更穩定。

Characteristic:

The old structure is driven by triode, and the actual frequency can be controlled within 2700 ± 300 HZ; The new structure is chip driven, and the actual frequency can be controlled within 2700 ± 200 HZ, Advantages The new structure uses IC drive frequency to control a smaller range, and the product quality is more stable.

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Rated Voltage 額定電壓	V_{DC}	12.0		
Operating Volt. 操作電壓	V_{DC}	7.0~15.0		
Mean Current 平均耗電流	mA	Max. 30		
Sound Output 輸出音壓	dBA	Min.85 (Typical 90)		
Resonant Frequency 諧振頻率	Hz	2700 ± 300		

Rated Voltage 額定電壓	V_{DC}	12.0		
Operating Volt. 操作電壓	V _{DC}	7.0~15.0		
Mean Current 平均耗電流	mA	Max. 30		
Sound Output 輸出音壓	dBA	Min.85 (Typical 90)		
Resonant Frequency 諧振頻率	Hz	2700 ± 200		

Estimated effective date: from 1/1/2023

Should you require samples for evaluation or record, please feel free to let our sales know. Sales contact: Emily Chen (Email: emilychen@kingstate.com.tw)

Sincerely yours

Gong Qin

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